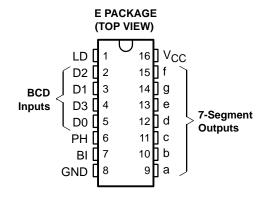
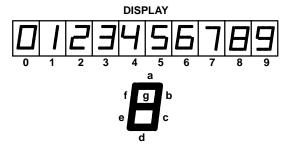
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- 4.5-V to 5.5-V V_{CC} Operation
- Input Latches for BCD Code Storage
- Blanking Capability
- Phase Input for Complementing Outputs
- Fanout (Over Temperature Range)Standard Outputs 10 LSTTL Loads
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction, Compared to LSTTL Logic ICs
- Direct LSTTL Input Logic Compatibility,
 V_{II} = 0.8 V Maximum, V_{IH} = 2 V Minimum
- CMOS Input Compatibility, I $_{I} \le$ 1 μ A at V $_{OL}$, V $_{OH}$





description/ordering information

The CD74HCT4543 high-speed silicon-gate is a BCD-to-7 segment latch/decoder/driver designed primarily for directly driving liquid-crystal displays. While the latch enable (LD) is low, the latches are enabled to store the BCD inputs. When the latch enable is high, the latches are disabled, making the outputs transparent to the BCD inputs. The device has an active-high blanking input (BI) and a phase input (PH) to which a square wave is applied for liquid-crystal applications. This square wave also is applied to the backplane of the liquid-crystal display.

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	PDIP – E Tube		CD74HCT4543E	CD74HCT4543E

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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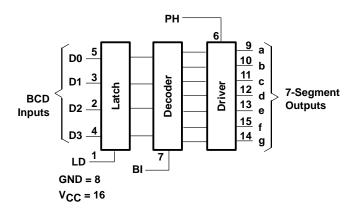


	CT			

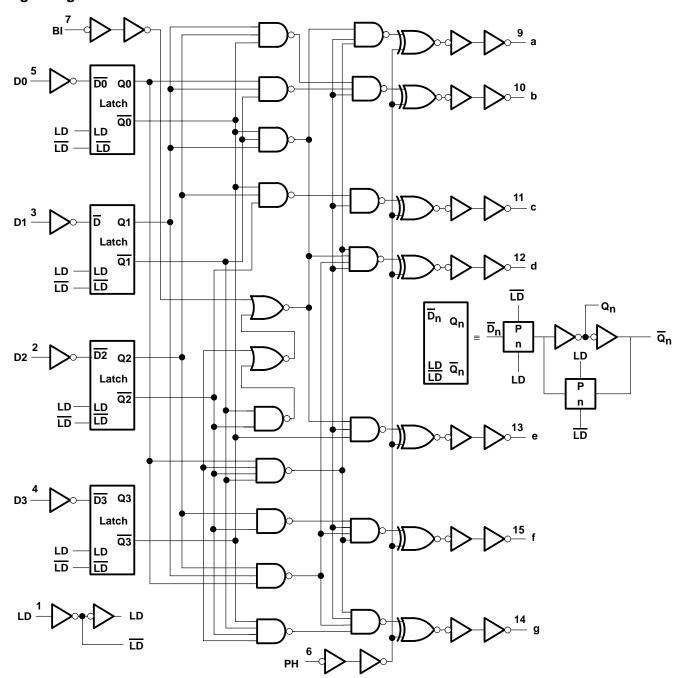
LD	ВІ	PH	D ₃	D ₂	D ₁	D ₀	а	b	С	d	е	f	g	Display
Х	Η	L	Х	Χ	Х	Χ	L	L	L	L	L	L	L	Blank
Н	┙	L	L	L	L	L	Η	Н	Н	Н	Н	Н	L	0
Н	┙	L	L	L	L	Н	L	Н	Н	L	L	L	L	1
Н	┙	L	L	L	Н	L	Η	Н	L	Н	Н	L	Н	2
Н	L	L	L	L	Н	Н	Н	Н	Н	Н	L	L	Н	3
Н	L	L	L	Н	L	L	L	Н	Н	L	L	Н	Н	4
Н	L	L	L	Н	L	Н	Н	L	Н	Н	L	Н	Н	5
Н	L	L	L	Н	Н	L	Н	L	Н	Н	Н	Н	Н	6
Н	L	L	L	Н	Н	Н	Н	Н	Н	L	L	L	L	7
Н	L	L	Н	L	L	L	Н	Н	Н	Н	Н	Н	Н	8
Н	L	L	Н	L	L	Н	Н	Н	L	Н	L	Н	Н	9
Н	L	L	Н	L	Н	L	L	L	L	L	L	L	L	Blank
Н	L	L	Н	L	Н	Н	L	L	L	L	L	L	L	Blank
Н	┙	L	Н	Н	L	L	L	L	L	L	L	L	L	Blank
Н	L	L	Н	Н	L	Н	L	L	L	L	L	L	L	Blank
Н	┙	L	Н	Н	Н	L	L	L	L	L	L	L	L	Blank
Н	┙	L	Н	Н	Н	Н	L	L	L	L	L	L	L	Blank
L	L	L	Х	Х	Х	Χ				†				†
As al	As above H As above				•	, The state of the	, The state of the	Inver	se of a	above			As above	

[†] Depends on BCD code previously applied when LD = high.

functional diagram



logic diagram



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absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input diode current, I_{IK} ($V_I < -0.5 \text{ V or } V_I > V_{CC} + 0.5 \text{ V}$) (see Note 1)	±20 mA
Output diode current, I_{OK} ($V_O < -0.5 \text{ V}$ or $V_O > V_{CC} + 0.5 \text{V}$) (see Note 1)	±20 mA
Continuous output source or sink current per output, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, $\hat{\theta}_{JA}$ (see Note 2)	67°C/W
At distance $1/16 \pm 1/32$ in. $(1.59 \pm 0.79 \text{ mm})$ from case for 10 s maximum	265°C
Unit inserted into a PC board (min. thickness 1/16 in., 1.59 mm)	
with solder contacting lead tips only	300°C
Storage temperature, T _{stg}	–65 to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		T _A = 2	25°C	T _A = -55°C TO 125°C		T _A = - TO 8		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		8.0		0.8	V
٧ı	Input voltage		VCC		VCC		VCC	V
٧o	Output voltage		VCC		VCC		VCC	V
t _t	Input transition (rise and fall) time		500		500		500	ns

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	Vcc	T _A = 25°C			T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT	
				MIN	TYP	MAX	MIN	MAX	MIN		
Vall	V_{OH} $V_{I} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -20 \mu A$ $I_{OH} = -4 \text{ mA}$		4.5 V	4.4			4.4		4.4		V
VOH			4.5 V	3.98			3.7		3.84		V
Val	V_{OL} $V_{I} = V_{IH} \text{ or } V_{IL}$ I_{C}		4.5 V			0.1		0.1		0.1	V
VOL			4.5 V			0.26		0.4		0.33	V
IĮ	$V_I = V_{CC}$ to GND		5.5 V			±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	5.5 V			8		160		80	μΑ
∆l _{CC} ‡	One input at V _{CC} – Other inputs at 0 or	2.1 V, VCC	4.5 V to 5.5 V		100	360		490		450	μΑ
C _i						10		10		10	pF

 $[\]ddagger$ Additional quiescent supply current per input pin, TTL inputs high, 1 unit load. For dual-supply systems, theoretical worst-case (V_I = 2.4 V, V_{CC} = 5.5 V) specification is 1.8 mA.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

HCT INPUT LOADING TABLE

INPUT	UNIT LOADS†
D0, D1, D2	1
D3, BI	0.5
PH	1.25
LD	1.5

[†]Unit Load is ΔICC limit specified in electrical characteristics table, e.g., 360 μA maximum

timing requirements over recommended operating free-air temperature range V_{CC} = 4.5 V (unless otherwise noted) (see Figure 1)

		T _A = 2	25°C	T _A = -	-55°C 25°C	T _A = -	40°C 5°C	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _W	Pulse duration, LD high	10		15		13		ns
t _{su}	Setup time, BCD inputs before LD \downarrow	12		18		15		ns
t _h	Hold time, BCD inputs before LD↓	8		12		10		ns

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	Vcc	т,	4 = 25°C	;	T _A = -		T _A = -		UNIT
	(INFUT)	(0011 01)	CALACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
	ר	Output	$C_L = 50 pF$	4.5 V			80		120		100	
	D _n	Output	C _L = 15 pF	5 V		33						
	LD	Output	C _L = 50 pF	4.5 V			77		116		96	
.	LD		C _L = 15 pF	5 V		32						20
^t pd	BI	Output	C _L = 50 pF	4.5 V			66		99		83	ns
	DI	Output	C _L = 15 pF	5 V		27						
	PH	Output	C _L = 50 pF	4.5 V			66		99		83	
	РΠ	Output	C _L = 15 pF	5 V		27						
t _t		Any	C _L = 50 pF	4.5 V			50		75		63	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

[PARAMETER	TYP	UNIT
Ī	C _{pd} [‡] Power dissipation capacitance	54	pF

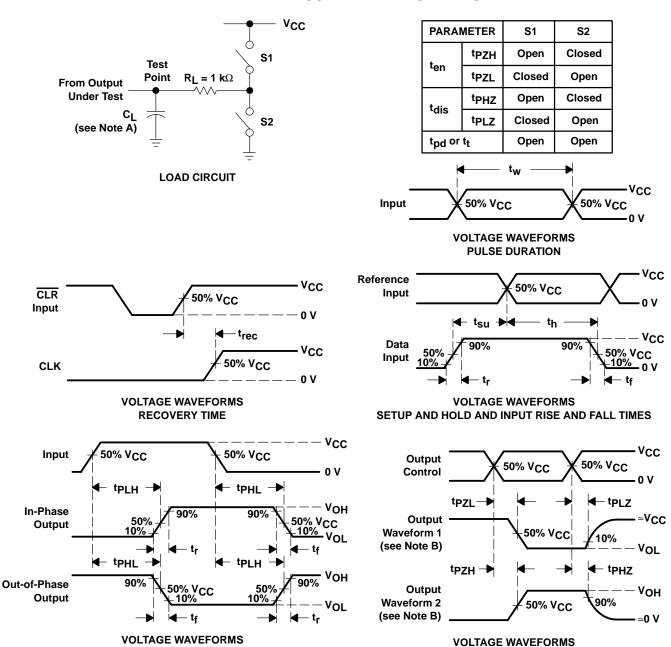
 $^{^\}ddagger C_{pd}$ is used to determine the dynamic power consumption, per package. PD = $C_{pd} \ ^VCC^2 \ ^f_i + \Sigma \ ^CL \ ^VCC^2 \ ^f_0$ where: f_i = input frequency

 f_O = output frequency C_L = output load capacitance

V_{CC} = supply voltage



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and test-fixture capacitance.

PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_f = 6$ ns, $t_f = 6$ ns.

OUTPUT ENABLE AND DISABLE TIMES

- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. t_{PZL} and t_{PZH} are the same as t_{en}.
- H. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



APPLICATION CIRCUITS

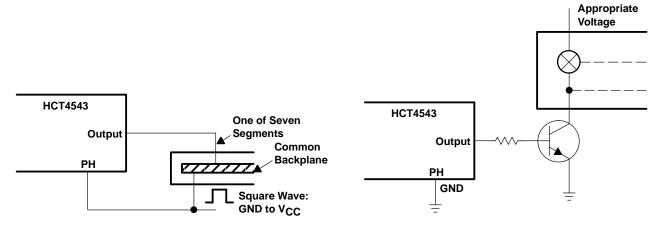


Figure 2. Connection to Liquid-Crystal Display (LCD)

Figure 3. Connection to Incandescent Display

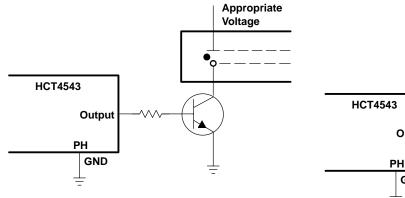


Figure 4. Connection to Gas-Discharge Display

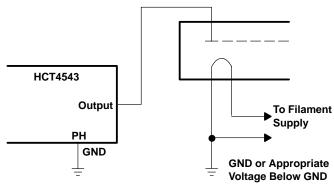


Figure 5. Connection to Fluorescent Display

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
CD74HCT4543E	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT4543E
CD74HCT4543E.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT4543E
CD74HCT4543EE4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT4543E

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

www.ti.com 23-May-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74HCT4543E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4543E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4543E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4543E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4543EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4543EE4	N	PDIP	16	25	506	13.97	11230	4.32

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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